



UPDATE CHANGE NOTIFICATIONGeneric Copy

10-Aug-2009**SUBJECT: ON Semiconductor Update Notification #16320****TITLE: Copper Wire in SOIC and TSSOP Packaged Products****PROPOSED FIRST SHIP DATE: 10-Aug-2009****AFFECTED CHANGE CATEGORY(S): Assembly Process****AFFECTED PRODUCT DIVISION(S): Analog****ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Matt Kas < Matt.Kas@onsemi.com >**SAMPLES:**

Contact your local ON Semiconductor Sales Office

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:Contact your local ON Semiconductor Sales Office or < Scott.Brow@onsemi.com >**NOTIFICATION TYPE:**

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 90 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

A Product Change Notification (PCN #16227) was published on 03-03-09 regarding the release of Copper Wire (in place of Gold Wire) on SOIC and TSSOP packages assembled at the Carmona, Philippines assembly location. This update notification is to notify customers that (4) devices were inadvertently omitted from the original PCN. Reliability Qualification and full electrical characterization over temperature has now been completed on the designated package qualification vehicles. Please reference PCN #16227 for more details.

AFFECTED DEVICE LIST

MC33067DWR2G

MC34067DWR2G

MC34067DWG

MC33067DWR2GH